

SECTION 28 05 26
GROUNDING AND BONDING FOR ELECTRONIC SAFETY AND SECURITY

PART 1 - GENERAL

1.1 DESCRIPTION

- A. This section specifies general grounding and bonding requirements of electronic safety and security installations for equipment operations.
- B. "Grounding electrode system" refers to all electrodes required by NEC, as well as including made, supplementary, grounding electrodes.
- C. The terms "connect" and "bond" are used interchangeably in this specification and have the same meaning.

1.2 RELATED WORK

- A. Section 28 05 11, REQUIREMENTS FOR ELECTRONIC SAFETY AND SECURITY INSTALLATIONS: General electrical requirements and items that are common to more than one section of Division 28.
- B. Section 28 05 13, CONDUCTORS AND CABLES FOR ELECTRONIC SAFETY AND SECURITY: Low Voltage power and lighting wiring.

1.3 SUBMITTALS

- A. Submit in accordance with Section 28 05 11, REQUIREMENTS FOR ELECTRONIC SAFETY AND SECURITY INSTALLATIONS.
- B. Shop Drawings:
 - 1. Sufficient information, clearly presented, shall be included to determine compliance with drawings and specifications.
 - 2. Include the location of system grounding electrode connections and the routing of aboveground and underground grounding electrode conductors.
- C. Test Reports: Provide certified test reports of ground resistance.
- D. Certifications: Two weeks prior to final inspection, submit four copies of the following to the Resident Engineer:
 - 1. Certification that the materials and installation is in accordance with the drawings and specifications.
 - 2. Certification, by the Contractor, that the complete installation has been properly installed and tested.

1.4 APPLICABLE PUBLICATIONS

Publications listed below (including amendments, addenda, revisions, supplements, and errata) form a part of this specification to the extent referenced. Publications are referenced in the text by the basic designation only.

- A. American Society for Testing and Materials (ASTM):

- B1-2001.....Standard Specification for Hard-Drawn Copper Wire
- B8-2004.....Standard Specification for Concentric-Lay-Stranded Copper Conductors, Hard, Medium-Hard, or Soft
- B. Institute of Electrical and Electronics Engineers, Inc. (IEEE):
 - 81-1983.....IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Ground System
- C. National Fire Protection Association (NFPA):
 - 70-2005.....National Electrical Code (NEC)
- D. Underwriters Laboratories, Inc. (UL):
 - 44-2005Thermoset-Insulated Wires and Cables
 - 83-2003Thermoplastic-Insulated Wires and Cables
 - 467-2004Grounding and Bonding Equipment
 - 486A-486B-2003Wire Connectors

PART 2 - PRODUCTS

2.1 GROUNDING AND BONDING CONDUCTORS

- A. Equipment grounding conductors shall be UL 83 insulated stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be solid copper. Insulation color shall be continuous green for all equipment grounding conductors, except that wire sizes 25 mm² (4 AWG) and larger shall be permitted to be identified per NEC.
- B. Bonding conductors shall be ASTM B8 bare stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be ASTM B1 solid bare copper wire.
- C. Isolated Power System: Type XHHW-2 insulation with a dielectric constant of 3.5 or less.

2.2 SPLICES AND TERMINATION COMPONENTS

Components shall meet or exceed UL 467 and be clearly marked with the manufacturer, catalog number, and permitted conductor size(s).

2.3 GROUND CONNECTIONS

- A. Below Grade: Exothermic-welded type connectors.
- B. Above Grade:
 - 1. Bonding Jumpers: compression type connectors, using zinc-plated fasteners and external tooth lockwashers.
 - 2. Ground Busbars: Two-hole compression type lugs using tin-plated copper or copper alloy bolts and nuts.

3. Rack and Cabinet Ground Bars: one-hole compression-type lugs using zinc-plated or copper alloy fasteners.

2.4 EQUIPMENT RACK AND CABINET GROUND BARS

Provide solid copper ground bars designed for mounting on the framework of open or cabinet-enclosed equipment racks with minimum dimensions of 4 mm thick by 19 mm wide (3/8 inch x ¾ inch).

2.5 GROUND TERMINAL BLOCKS

At any equipment mounting location (e.g. backboards and hinged cover enclosures) where rack-type ground bars cannot be mounted, provide screw lug-type terminal blocks.

2.6 SPLICE CASE GROUND ACCESSORIES

Splice case grounding and bonding accessories shall be supplied by the splice case manufacturer when available. Otherwise, use 16 mm² (6 AWG) insulated ground wire with shield bonding connectors.

2.7 COMPUTER ROOM GROUND

Provide 50mm² (1/0 AWG) bare copper grounding conductors bolted at mesh intersections to form an equipotential grounding grid. The equipotential grounding grid shall form a 600mm (24 inch) mesh pattern. The grid shall be bonded to each of the access floor pedestals.

PART 3 - EXECUTION

3.1 GENERAL

- A. Ground in accordance with the NEC, as shown on drawings, and as hereinafter specified.
- B. System Grounding:
 - 1. Secondary service neutrals: Ground at the supply side of the secondary disconnecting means and at the related transformers.
 - 2. Separately derived systems (transformers downstream from the service entrance): Ground the secondary neutral.
 - 3. Isolation transformers and isolated power systems shall not be system grounded.
- C. Equipment Grounding: Metallic structures (including ductwork and building steel), enclosures, raceways, junction boxes, outlet boxes, cabinets, machine frames, and other conductive items in close proximity with electrical circuits shall be bonded and grounded.

3.2 INACCESSIBLE GROUNDING CONNECTIONS

Make grounding connections, which are buried or otherwise normally inaccessible (except connections for which periodic testing access is required) by exothermic weld.

3.3 CORROSION INHIBITORS

When making ground and ground bonding connections, apply a corrosion inhibitor to all contact surfaces. Use corrosion inhibitor appropriate for protecting a connection between the metals used.

3.4 CONDUCTIVE PIPING

- A. Bond all conductive piping systems, interior and exterior, to the building to the grounding electrode system. Bonding connections shall be made as close as practical to the equipment ground bus.
- B. In operating rooms and at intensive care and coronary care type beds, bond the gases and suction piping, at the outlets, directly to the room or patient ground bus.

3.5 COMPUTER ROOM GROUNDING

- A. Conduit: Ground and bond metallic conduit systems as follows:
 - 1. Ground metallic service conduit and any pipes entering or being routed within the computer room at each end using 16 mm² (6AWG) bonding jumpers.
 - 2. Bond at all intermediate metallic enclosures and across all joints using 16 mm² (6 AWG) bonding jumpers.
 - 3. Bond every metallic conduit that penetrates the plan of the raised floor to the raised floor stringer system as follows:
 - a. Unpainted Supports Attached to Raised Floor System: When conduit/strut clamps are used to attach conduit to Unistrut, no additional bonding is required.
 - b. Unpainted Supports Not Attached to Raised Floor System: When conduit/strut clamps are used to attach conduit to Unistrut, use 16 mm² (6 AWG) bonding jumpers to connect Unistrut to the raised floor system.
 - c. Painted Supports: Use 16 mm² (6 AWG) bonding jumpers to connect conduit to the stringer system. Mount a push-type conduit fastener onto every metallic conduit. Place fasteners no higher or lower than 75 mm (3 inches) from the raised floor stringer.
- B. Equipotential Grounding Grid:
 - 1. Install a bolted stringer system to serve as the computer room equipotential grounding grid.
 - 2. If a bolted stringer system is not provided, install equipotential grounding grid in a 600 mm square grid consisting of 50 mm² (1/0 AWG) bare copper conductor welded at the intersection of each grid.

3. Attach the equipotential ground grid to the room signal ground bus using a 50 mm² (1/0 AWG) bare copper grounding conductor.

3.6 WIREWAY GROUNDING

- A. Ground and Bond Metallic Wireway Systems as follows:
 1. Bond the metallic structures of wireway to provide 100 percent electrical continuity throughout the wireway system by connecting a 16 mm² (6 AWG) bonding jumper at all intermediate metallic enclosures and across all section junctions.
 2. Install insulated 16 mm² (6 AWG) bonding jumpers between the wireway system bonded as required in paragraph 1 above, and the closest building ground at each end and approximately every 16 meters (50 feet).
 3. Use insulated 16 mm² (6 AWG) bonding jumpers to ground or bond metallic wireway at each end at all intermediate metallic enclosures and cross all section junctions.
 4. Use insulated 16 mm² (6 AWG) bonding jumpers to ground cable tray to column-mounted building ground plates (pads) at each end and approximately every 15 meters.

3.7 GROUND RESISTANCE

- A. Grounding system resistance to ground shall not exceed 5 ohms. Make necessary modifications or additions to the grounding electrode system for compliance without additional cost to the Government. Final tests shall assure that this requirement is met.
- B. Resistance of the grounding electrode system shall be measured using a four-terminal fall-of-potential method as defined in IEEE 81. Ground resistance measurements shall be made before the electrical distribution system is energized and shall be made in normally dry conditions not less than 48 hours after the last rainfall. Resistance measurements of separate grounding electrode systems shall be made before the systems are bonded together below grade. The combined resistance of separate systems may be used to meet the required resistance, but the specified number of electrodes must still be provided.
- C. Services at power company interface points shall comply with the power company ground resistance requirements.

3.8 GROUNDING FOR RF/EMI CONTROL

- A. Install bonding jumpers to bond all conduit, cable trays, sleeves and equipment for low voltage signaling and data communications circuits.

Bonding jumpers shall consist of 100 mm (4 inches) wide copper strip or two 6 mm² (10 AWG) copper conductors spaced minimum 100 mm (4 inches) apart. Use 16 mm² (6 AWG) copper where exposed and subject to damage.

- B. Comply with the following when shielded cable is used for data circuits.
1. Shields shall be continuous throughout each circuit.
 2. Connect shield drain wires together at each circuit connection point and insulate from ground. Do not ground the shield.
 3. Do not connect shields from different circuits together.
 4. Shield shall be connected at one end only. Connect shield to signal reference at the origin of the circuit. Consult with equipment manufacturer to determine signal reference.

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